

PGA to Surface Mount Foot Print, Test Head

- Probes Directly to Fine-Pitch SMT Pads on Chip-Users Circuit Board
- Non-Permanent Connection to SMT Pads
- Pin-Compatible With Existing PGA Test Set-Ups

Interconnect Systems, Inc. has developed a PGA to QFP adapter mechanism ("Emulator Test Head") which allows users of Intel i960[®] processors to probe directly to the bare SMT footprint on their board assembly, thus solving a major test issue for high-end chip users contemplating the transition to a QFP package from a PGA package.

In its basic form, the test head consists of a PGA LIF socket on one side (to interface with the test hardware), internal translation circuitry, and an array of fine-pitch low force spring probes (to mate with the SMT pads on the printed circuit board).

PROCESSORS SUPPORTED:
i960 Processor Family

CONTACT:
Glen Griswold
Interconnect Systems Inc.
2162 Union Place
P.O. Box 1089
Simi Valley, CA 93065
Phone: (805) 581-5626
FAX: (805) 581-5032

